



Type Document	Product Specification	Revised /Edition	E
Date Issued	2018/5/22	Data Revised	2019/01/22
Subject: JS-5008-XXXX / JS-5009A-XXXX / JS-5009B-XXXX Pitch 5.0mm DIP Series Wire to Board Connector			Issued By: Engineering Dept.

*This specification is referred to the 5.00mm
DIP series wire to board connector.*

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Product Name/Part Number & Drawing Number.

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1.0 Product Name/Part Number & Drawing Number:

Product Name		Part Number	Drawing Number
Wafer	Straight(DIP)	JS-5008-XX	JS-5008-XX
Housing		JS-5009A-XX	JS-5009A-XX
		JS-5009B-XX	JS-5009B-XX

Note: (xx) The number of the circuits.

2.0 Construction/Material & Surface Finish:

Construction and dimensions shall be in accordance with the referenced drawing.
 Material and surface finish shall be specified as listing.

Part Name		Material	Surface Finish
Wafer	Base	Nylon 66+GF	UL 94V-0
	Pin	Brass	Tin-Plated
Housing	Housing	Nylon 66	UL 94V-0

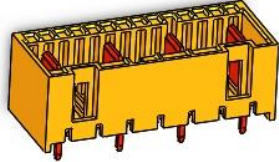
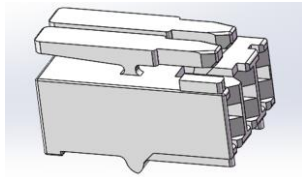
3.0 Characteristic:

Item		Standard	
3.1	Max Current	16A AC/DC (With AWG #14~ AWG #18 is applied)	
3.2	Rated Voltage	250 VAC	
3.3	Ambient Temperature Range	-40°C~+120°C	
3.4	Applicable Wire	3.4.1	Conductor Construction Size: AWG #14~#18
		3.4.2	Wire Insulation O.D.: 1.3mm ~ 1.7mm
3.5	Applicable Printed Circuit Board (PCB)	3.5.1	Thickness: 1.6 mm
		3.5.2	Hole Size:1.30 ± 0.05 mm
		3.5.3	Hole Pitch: 5.00 ± 0.05 mm



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4.0 Specimen:

Part Name		Part Number	Picture or Photograph
Wafer	Straight (DIP)	JS-5008-XX	
Housing		JS-5009A-XX JS-5009B-XX	

5.0 Applicable Standards:

- MIL-STD-202 Methods by test of connectors for electronic equipment.**
- MIL-STD-1344 Test methods for electrical connectors.**

6.0 Mechanical Performance:

Item	Test Condition	Requirement
6.1 Contact Retention Force	Withdraw with contact terminal at the speed rate of 25mm/minute.	2.5kgf / Min.
6.2 Glow wire test	IEC 60695-2-11	Tested part shall have rating of 750° C With no flame
6.3 Insertion & Retention Force	Insert and withdraw with connectors at the speed rate of 25mm/minute. (EIA/ECA 364-13D)	Refer to paragraph 9.1



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7.0 Electrical Performance:

Item		Test Condition	Requirement
7.1	Contact Resistance	A maximum voltage of 20mV and a maximum current of 100mA are applied to the Mate connectors. (EIA/ECA 364-23C)	Initial: 20 milliohms Max
7.2	Insulation Resistance	Apply 500V D/C to any two adjacent contacts to measure the insulation resistance. (EIA 364-21C)	Initial: 5000 megohms Min. After:1000 megohms Min
7.3	Withstanding Voltage	Apply 3000V A/C (rms) for 1 minute to the adjacent terminal and ground of the Mate connectors. (EIA 364-20C)	No breakdown or flashover.



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8.0 Environmental Performance:

Item		Test Condition	Requirement
8.1	Durability	Mate Connectors up 30 Cycles at a Maximum rate of 10 cycles Per minute prior to environmental test (EIA/ECA 364-09C)	(After the test) Contact Resistance: 40 milliohms Max.
8.2	Vibration	Frequency: 5~500~5 Hz/minute. Amplitude: 7.5 mm. Direction: 1. Axis of up and down. 2. Axis of right the left. 3. Axis of front and back. Period: 2 hours for each direction. (EIA/ECA 364-28E-Condition I)	(After the test) Contact Resistance: 40 milliohms Max.
			No discontinuity current is longer than 1 microsecond.
8.3	Humidity Steady State	Temperature: 40±2°C. Humidity: 90%~95% (RH). Period: 96 hours continuously. (EIA 364-31B Conditions III . Method A)	(After the test) Contact Resistance: 40 milliohms Max. Withstanding Voltage: 1000 V No breakdown or flashover.



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Item		Test Condition	Requirement
8.4	Heat Aging	Temperature: $85 \pm 3^{\circ}\text{C}$. Period: 96 hours continuously. (EIA 364-17B Conditions III . Method A)	(After the test) Contact Resistance: 40 milliohms Max.
8.5	Thermal Shock	One Cycle Consists Of: - $55(+ 0 - 3)^{\circ}\text{C}$ for 30 minutes. + $85(+ 3 - 0)^{\circ}\text{C}$ for 30 minutes. Time of Cycles: 25 Cycles. (EIA/ECA 364-32D Conditions I . Method A)	Same as paragraph 8.3
8.6	Salt Spray	Temperature: $35 \pm 2^{\circ}\text{C}$. Density: 5 % in weight. Period: Terminal or contact (Stamping after tin plated for 12 hours) ; Terminal or contact (Stamping before tin plated for 24 hours)	(After the test) Insulation Resistance: 40 milliohms Max.
8.7	Solder Ability	Solder Temperature: $245 \pm 5^{\circ}\text{C}$ Immersion Period: 3 ± 0.5 Seconds (EIA 364-52B)	Solder entirely 95% of immersed area must show no voids or pinholes.



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Item	Test Condition	Requirement
8.8	<p>Resistance To Soldering Heat</p> <p>By reflow soldering:</p> <div style="text-align: center;"> <p>TEMPERATURE CONDITION GRAPH (TEMPERATRE ON BOARD PATTERN SIDE)</p> </div> <p>By soldering :</p> <p>Solder Temperature: 260 ± 5°C.</p> <p>Immersion Period: 5 ± 1 Seconds</p> <p>Method: 0.5mm (SMT) / 1.5mm (DIP) from terminal tip and fitting nail tip.</p>	<p>No deformation or damage.</p>

9.0 Insertion Force (I.F.) & Retention Force (R.F.)

9.1 Requirement:

No. Of Circuits	AT INITIAL		AT 50TH	No. Of Circuits	AT INITIAL		AT 50TH
	I.F. (MAX)	R.F. (MIN)	R.F. (MIN)		I.F. (MAX)	R.F. (MIN)	R.F. (MIN)
02	8.0	2.0	2.0				
03	8.5	2.5	2.5				
04	9.0	3.0	3.0				
05							
06							



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10.0 Remark: Any change or revision for the product specification will not be announced in advance. Please contact our sales representative for the latest information.